

REMARKS

In view of the following remarks, Applicant respectfully requests reconsideration and allowance of the subject application.

§103 Rejections

Claims 91, 95-97, 77, 80-83, 85 and 86 are rejected under 35 U.S.C. §103(a) as allegedly being unpatentable over US Patent No. 5,419,712 to Bellomo et al. in view of US Patent No. 5,451,815 to Taniguchi et al. Claims 91, 95-97, 77, 80-83, 85 and 86 have been canceled and the rejection is therefore moot.

New Claims Allowable

New claims 98-111 have been added and are allowable over the cited references for at least the reasons that the references do not teach the following as recited in claim 98:

a single chip package configured to house a single integrated circuit chip;

a first clip arm extending from a first side of the chip package;
a second clip arm extending from a second side of the chip package, the first side and the second side being opposite one another;

a plurality of flexible leads, each flexible lead having a length, a first end connected to a third side of the chip package, and a second end disconnected from the third side of the chip package and extending away from the chip package through the length, each flexible lead configured to provide mechanical and electrical connection between the single integrated circuit chip and a circuit board; and

an indentation in the chip package into which the second end of the flexible leads are extendable.

1 Bellomo teaches an edge card interconnection system that provides
2 “enhanced electrical interconnection between a module and a circuit board.”
3 (Abstract; col. 2, lines 32-34; emphasis added). “Edge card interconnection
4 systems are known for interconnecting modules with electronic printed circuit
5 boards. Known modules, such as single in-line memory modules (SIMM) and
6 electronic sub-assembly daughter board modules require interconnection with a
7 main electronic module or mother board, which typically involves implementing
8 an edge connection scheme wherein *contact pads on the edge of the module* are
9 engagable with contacts in a connector or socket on the main module or
10 motherboard.” (col. 1, lines 14-23, emphasis added). Bellomo states that contact
11 pads (34) are “disposed along an edge of a module 36 to be electrically
12 interconnected with a main circuit board 33.” Thus Bellomo does not teach leads
13 having “a length, a first end connected to a third side of the chip package, and a
14 second end disconnected from the third side of the chip package and extending
15 away from the chip package through the length”. Rather, it is clear from Bellomo,
16 e.g., at Fig. 5, that contact pads 34 are flush with a module, and do not have a
17 second end which extends away from the module.

18 In addition to various other elements of claim 98 not taught by Bellomo or
19 Taniguchi, neither reference teaches “an indentation in the chip package into
20 which the second end of the flexible leads are extendable”. Taniguchi teaches
21 “wiring lines 14” that are not flexible. Further, Taniguchi’s “wiring lines 14” are
22 not extendable into an indentation in a chip package.

23 For at least these reasons, new claim 98 is allowable over the cited
24 references. Furthermore, claims 99-111 depend from claim 98 and are therefore
25 allowable by virtue of at least this dependency.

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2 **Conclusion**

3 All pending claims are in condition for allowance. Applicant respectfully
4 requests reconsideration and prompt issuance of the subject application. If any
5 issues remain that prevent issuance of this application, the Examiner is urged to
6 contact the undersigned attorney before issuing a subsequent Action.

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8 Respectfully Submitted,

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10 Dated: 5/19/04

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